

# H-Bridge Driver IC TLE7182EM

**Evaluation Board** 

# **Application Note**

Rev 1.2, 2012-03-20

**Automotive Power** 



**Abstract** 

#### 1 Abstract

Note: The following information is given as a hint for the implementation of the device only and shall not be regarded as a description or warranty of a certain functionality, condition or quality of the device.

This Application Note is intended to provide information about the TLE7182EM Evalution Board Revision 1.1. The board is designed to facilitate the evaluation of the Infineon H-bridge driver TLE7182EM.

This document includes a board description, a quick start guide, the schematics and the layout of the board. It is assumed that the reader is familiar with the driver IC data sheet.

The board itself can be ordered using the usual Infineon Technologies sales channels.

Please make sure that the revision of your evaluation board and the board revision described in this document (1.1) match before you get started.

Application Note 2 Rev 1.2, 2012-03-20



**Board description** 

## 2 Board description

Besides the H-bridge driver itself, the TLE7182EM Evalution Board contains 5 N-Channel Power MOSFETs, a current sense shunt resistor and other additional components like a 5V regulator to allow operation without a lot of external equipment. It is designed for automotive 12V applications. This chapter describes all parts of the board. Schematics and layout are covered in detail in **Chapter 4** 

#### 2.1 Overview

Figure 1 contains the top view of the board.

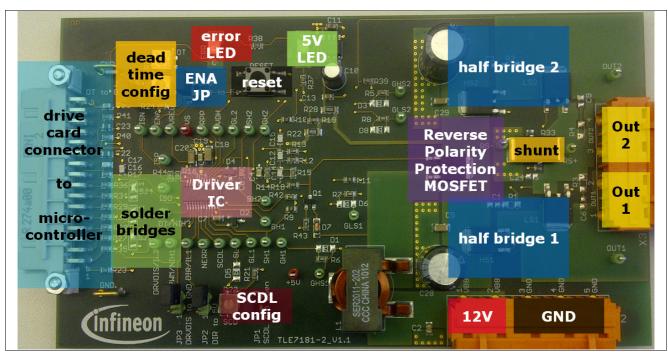


Figure 1 top view of the TLE7182EM Evalution Board

#### 2.2 Power Supply

The power supply of the board and the load (=motor) has to be connected to the connector X2. Please see **Figure 1** for the required polarity.

#### 2.3 Power Stages and Phase Outputs

Each of the two power stages contain two IPD90N04S04-02 n-channel MOSFETs. One of them is used as a low side switch, the other one as a high side switch. Two DC link capacitors (220µF and 2.2µF) have been added. It is possible to add snubber circuits for high side as well as the low side MOSFETs but they are not mounted by default. The phase outputs are available on the connector X3.

Figure 2 shows the power stage components in detail.

Application Note 3 Rev 1.2, 2012-03-20



**Board description** 

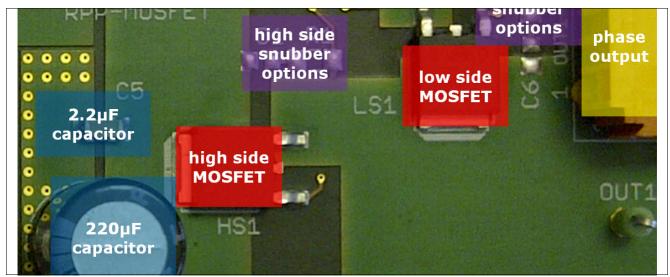


Figure 2 power stage

#### 2.4 Status LEDs

The TLE7182EM Evalution Board has two status LEDs. The green 5V LED indicates that the 5V voltage regulator is working correctly. The red ERR LED will light up if there is a warning or an error indication of the bridge driver.

### 2.5 Solder Bridges

The PCB of the TLE7182EM Evalution Board is also used for the TLE7181EM Evalution Board. The solder bridges have to be set according to **Figure 3**.

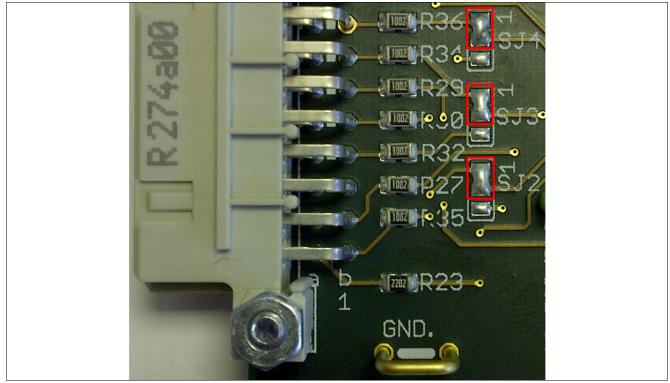


Figure 3 required solder bridges configuration for TLE7182EM

Application Note 4 Rev 1.2, 2012-03-20



**Board description** 

#### 2.6 Drive Card Connector to Microcontroller

The drive card connector is the interface to the microcontroller. It contains the 5V supply voltage for the microcontroller as well as all relevant connections to input and output pins of the bridge driver. Please see the schematics in **Chapter 4** for a detailed pin description. All jumpers except JP1 (SCDL open) have to be open if a microcontroller is used.

#### 2.7 Jumpers, Buttons and Potentiometers

The TLE7182EM Evalution Board has several jumpers to simplify usage without a microcontroller, to allow tweaking of the short circuit detection level (SCDL) and for testing purposes.

#### 2.7.1 ENA jumper JP5 and Reset Button

The ENA pin of the driver IC enables it. ENA can be set to 5V by setting the jumper JP5. ENA can be temporarily set to GND by pressing the reset button. This will reset the IC. If the device is used with a microcontroller, JP5 has to be open in order not to override the ENA signal coming from the microcontroller.

#### 2.7.2 R25. R31 and JP4

R25, R31 and JP4 are not used.

#### 2.7.3 Short Circuit Detection Level Configuration

The short circuit detection level can be adjusted with the SCD potentiometer next to the jumper JP1. It has to be assured that SCDL is within the range specified in the data sheet.

The jumper JP1 has to be set in normal operation mode. In order to test the SCD open pin detection, JP1 can be removed. In this case the ERR LED has to light up.

#### 2.7.4 JP2

Setting JP2 sets the signal input IL1 to high. JP2 has to be open for normal operation with TLE7182EM.

#### 2.7.5 JP3

JP3 sets the signal input IL2 to low. It has to be open for normal operation with TLE7182EM.

Application Note 5 Rev 1.2, 2012-03-20



**Quick Start Guide** 

#### 3 Quick Start Guide

#### 3.1 Before You Begin

Please make sure that the revision of your evaluation board and the board revision described in this document (1.1) match before you get started. The revision number is printed on the PCB as shown in Figure 4.

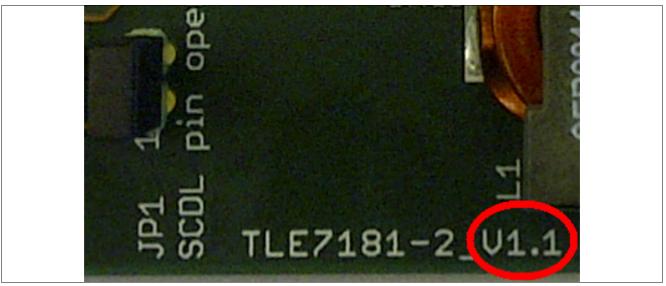


Figure 4 board revision

#### 3.2 Preparation

The same PCB is used for both, the TLE7181EM Evalution Board and the TLE7182EM Evalution Board. Please check whether the correct H-bridge driver IC is mounted on the PCB.

Please set the solder bridges according to Chapter 2.5.

#### 3.3 Simple Example without a Microcontroller

To drive an external DC-brush motor at the phase outputs, only a few steps are required.

- set jumper JP1 (see Chapter 2.7.3) to avoid the SCDL open pin error
- set jumper JP5 (see Chapter 2.7.1) to set the ENA pin to high
- open JP2 and JP3 which are not used for TLE7182EM
- connect a 12V power supply according to Chapter 2.2
- connect a DC-brush motor to the outputs OUT1 and OUT2
- if the red ERR LED indicates a problem, make sure that the SCDL voltage is within the range specified in the data sheet. At the time of writing this document, the current data sheet defines a valid range from 0.2..2.0V. If the SCDL voltage is not within this range, please change it as described in **Chapter 2.7.3**
- if the red ERR LED still indicates a problem, please go through the error conditions specified in the data sheet. If one or more of them are met, please resolve them
- make sure that the bootstrap capacitors are charged by switching on the low side MOSFETs. The PINs of the
  drive card connector corresponding to IL1 and IL2 (see Figure 5) have to be set to high to do so
- apply valid PWM patterns to the PINs of the driver card connector corresponding to the input signals IL1, IH1,
   IL2 and IH2
- now the MOSFETs should be switching as defined by the input signals

Application Note 6 Rev 1.2, 2012-03-20



**Quick Start Guide** 

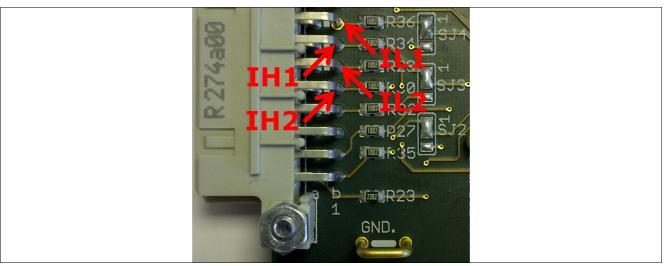


Figure 5 Driver Card Connector PINs for IL1 (X1-B8), IH1(X1-B7), IL2 (X1-B6) and IH2 (X1-B5)

Application Note 7 Rev 1.2, 2012-03-20



## 4 schematics and layout

Figure 6 contains the schematics. Table 1 contains the part list.

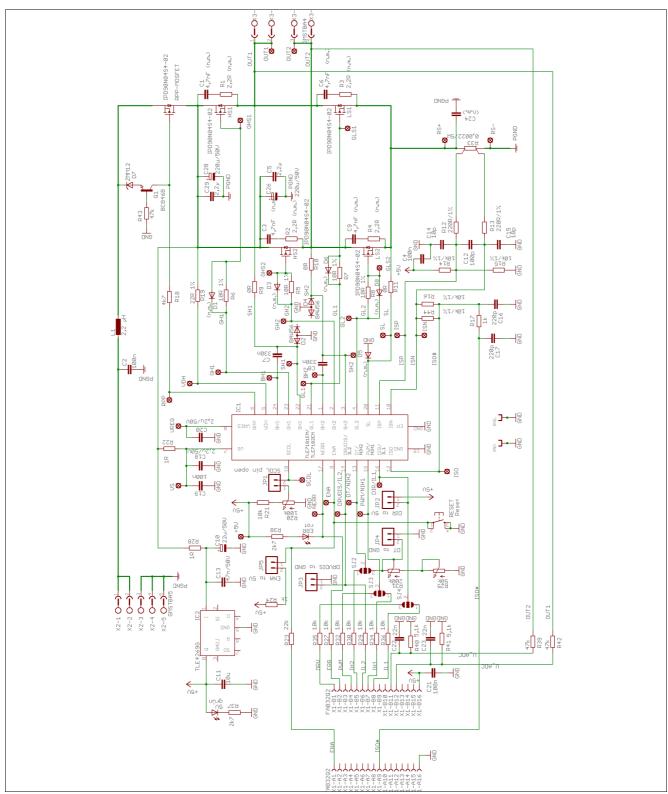


Figure 6 schematics

Application Note 8 Rev 1.2, 2012-03-20



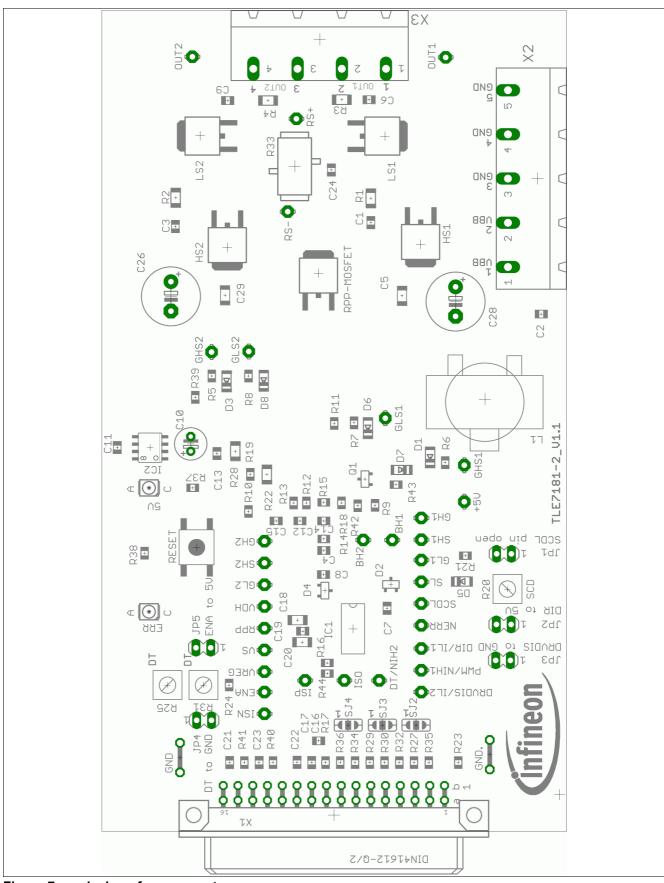


Figure 7 placing of components

Application Note 9 Rev 1.2, 2012-03-20



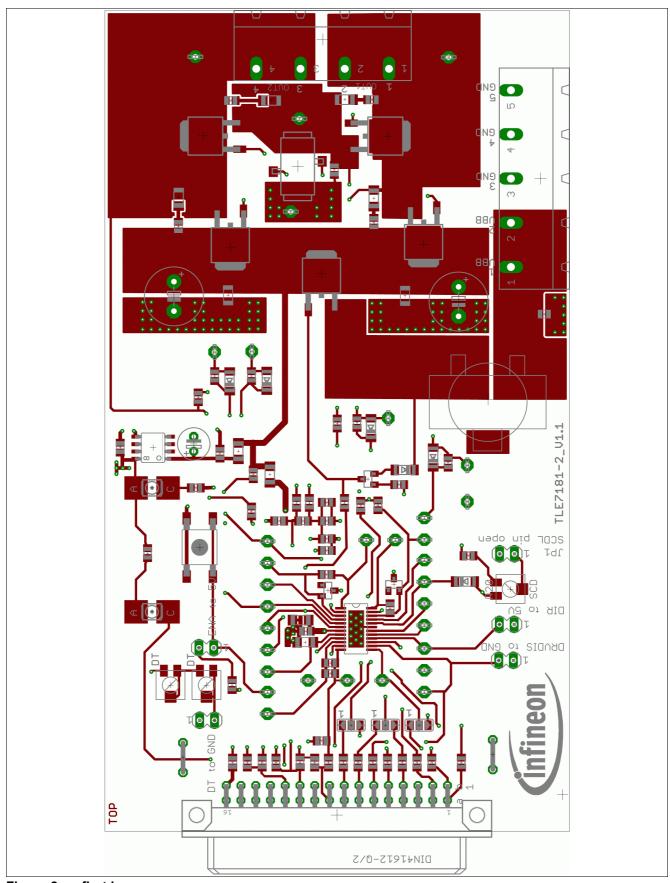


Figure 8 first layer



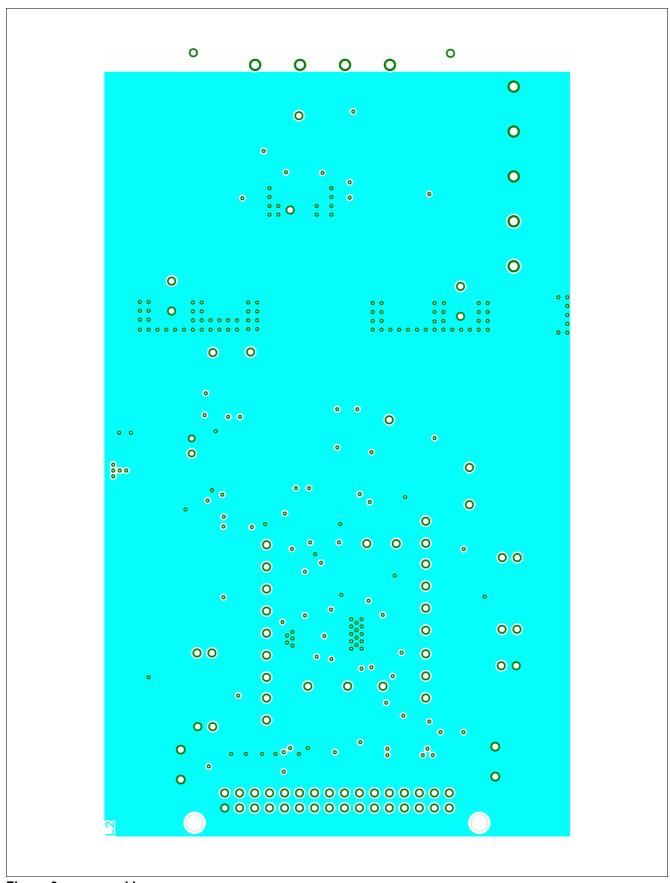


Figure 9 second layer

Application Note 11 Rev 1.2, 2012-03-20



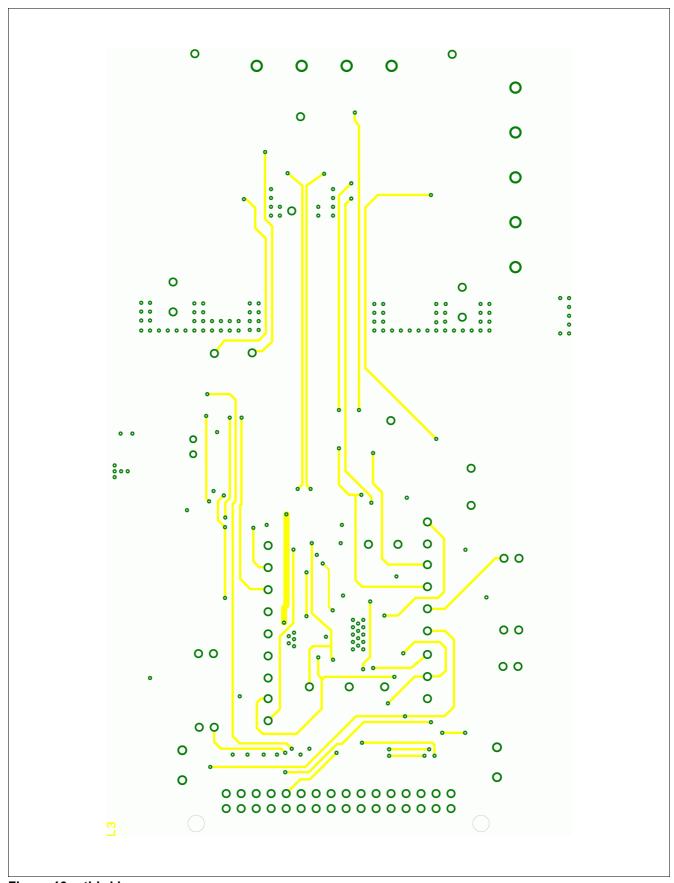


Figure 10 third layer

Application Note 12 Rev 1.2, 2012-03-20



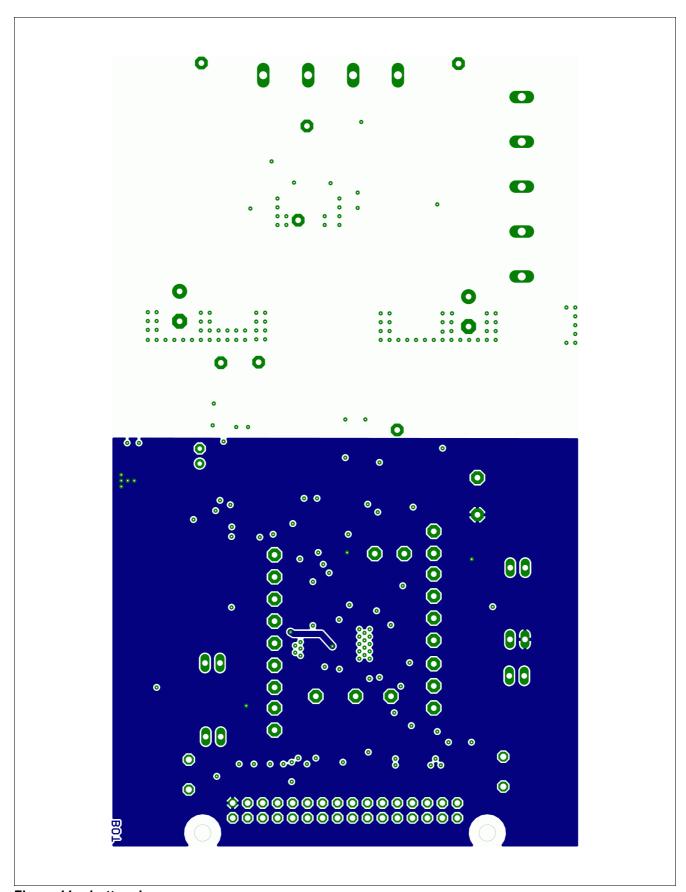


Figure 11 bottom layer

Application Note 13 Rev 1.2, 2012-03-20

Table 1 part list (major components only)

Table 1	part list (majo	r components only)	
Part		Value	Package
C1		4,7nF (n.m.)	C0805
C2		100n	C0805
C3		4,7nF (n.m.)	C0805
C4		100n	C0805
C5		2,2µ	C1210
C6		4,7nF (n.m.)	C0805
C7		330n	C0805
C8		330n	C0805
C9		4,7nF (n.m.)	C0805
C10		22u/50V	E2,5-6
C11		10u	C0805
C12		100p	C0805
C13		47n/50V	C1210
C14		10p	C0805
C15		10p	C0805
C16		220p	C0805
C17		220p	C0805
C18		2,2u/50V	C1206
C19		100n	C0805
C20		2,2u/50V	C1206
C21		100n	C0805
C22		22n	C0805
C23		22n	C0805
C24		(n.m.)	C0805
C26		220u/50V	E5-10,5
C28		220u/50V	E5-10,5
C29		2,2µ	C1210
D1		(n.m.)	MINIMELF
D2		BAW56	SOT23C
D3		(n.m.)	MINIMELF
D4		BAW56	SOT23C
D5		(n.m.)	MINIMELF
D6		(n.m.)	MINIMELF
D7		ZMM12	MINIMELF
D8		(n.m.)	MINIMELF
HS1		IPD90N04S4-02	TO252-3-1
HS2		IPD90N04S4-02	TO252-3-1
IC1		TLE7181EM	SSPO24_EXPOSED
IC2		TLE4269	P-DSO08
L1		2,2 μΗ	SER2000
			1



Table 1 part list (major components only)

Table 1	Table 1 part list (major components only)				
Part		Value	Package		
LS1		IPD90N04S4-02	TO252-3-1		
LS2		IPD90N04S4-02	TO252-3-1		
Q1		BC846B	SOT23		
R1		2,2R (n.m.)	R1206		
R2		2,2R (n.m.)	R1206		
R3		2,2R (n.m.)	R1206		
R4		2,2R (n.m.)	R1206		
R5		10R 1%	R0805		
R6		10R 1%	R0805		
R7		10R 1%	R0805		
R8		10R 1%	R0805		
R9		0R	R0805		
R10		0R	R0805		
R11		0R	R0805		
R12		220R/1%	R0805		
R13		220R/1%	R0805		
R14		10k/1%	R0805		
R15		10k/1%	R0805		
R16		10k/1%	R0805		
R17		1k	R0805		
R18		4k7	R0805		
R19		22R 1%	R0805		
R20		100k	TS53Y		
R21		10k	R0805		
R22		1R	R1206		
R23		22k	R0805		
R24		1k	R0805		
R25		47k	TS53Y		
R27		10k	R0805		
R28		1R	R1206		
R29		10k	R0805		
R30		10k	R0805		
R31		220k	TS53Y		
R32		10k	R0805		
R33		0,002/5W	SMV		
R34		10k	R0805		
R35		10k	R0805		
R36		10k	R0805		
R37		2k7	R1206		
R38		2k7	R1206		
R39		47k	R0805		
-		<del>-</del>			



Table 1 part list (major components only)

Part	Value	Package
R40	5,1k	R0805
R41	5,1k	R0805
R42	47k	R0805
R43	47k	R0805
R44	10k/1%	R0805
RPP-MOSFET	IPD90N04S4-02	TO252-3-1

**Revision History** 

## 5 Revision History

#### **TLE7182EM Evalution Board**

**Revision History: Rev 1.2, 2012-03-20** 

Previous Version(s):1.1

Page	Subjects (major changes since last revision)				
-	several changes related to updated Evaluation Board revision 1.1				
-	editorial changes				

Application Note 17 Rev 1.2, 2012-03-20

Edition 2012-03-20

Published by Infineon Technologies AG 81726 Munich, Germany © 2012 Infineon Technologies AG All Rights Reserved.

#### **LEGAL DISCLAIMER**

THE INFORMATION GIVEN IN THIS APPLICATION NOTE IS GIVEN AS A HINT FOR THE IMPLEMENTATION OF THE INFINEON TECHNOLOGIES COMPONENT ONLY AND SHALL NOT BE REGARDED AS ANY DESCRIPTION OR WARRANTY OF A CERTAIN FUNCTIONALITY, CONDITION OR QUALITY OF THE INFINEON TECHNOLOGIES COMPONENT. THE RECIPIENT OF THIS APPLICATION NOTE MUST VERIFY ANY FUNCTION DESCRIBED HEREIN IN THE REAL APPLICATION. INFINEON TECHNOLOGIES HEREBY DISCLAIMS ANY AND ALL WARRANTIES AND LIABILITIES OF ANY KIND (INCLUDING WITHOUT LIMITATION WARRANTIES OF NON-INFRINGEMENT OF INTELLECTUAL PROPERTY RIGHTS OF ANY THIRD PARTY) WITH RESPECT TO ANY AND ALL INFORMATION GIVEN IN THIS APPLICATION NOTE.

#### Information

For further information on technology, delivery terms and conditions and prices, please contact the nearest Infineon Technologies Office (www.infineon.com).

#### Warnings

Due to technical requirements, components may contain dangerous substances. For information on the types in question, please contact the nearest Infineon Technologies Office.

Infineon Technologies components may be used in life-support devices or systems only with the express written approval of Infineon Technologies, if a failure of such components can reasonably be expected to cause the failure of that life-support device or system or to affect the safety or effectiveness of that device or system. Life support devices or systems are intended to be implanted in the human body or to support and/or maintain and sustain and/or protect human life. If they fail, it is reasonable to assume that the health of the user or other persons may be endangered.